## 2SD1385

### Silicon NPN triple diffusion planar type

For low-frequency output amplification

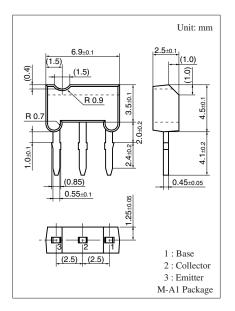
#### ■ Features

- High collector-base voltage (Emitter open) V<sub>CBO</sub>
- Large collector power dissipation P<sub>C</sub>
- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- M type package, allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board.

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	400	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	400	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	5	V	
Collector current	$I_{C}$	100	mA	
Peak collector current	$I_{CP}$	200	mA	
Collector power dissipation *	P <sub>C</sub>	1	W	
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

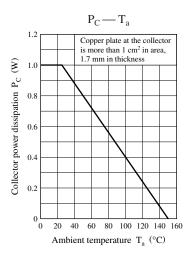
Note) \*: Printed circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion

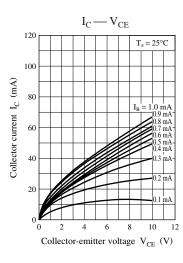


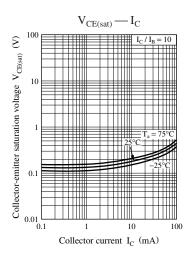
### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

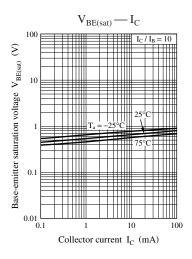
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 100 \ \mu A, I_E = 0$	400			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 500 \mu\text{A},  I_B = 0$	400			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 100 \ \mu A, I_C = 0$	5			V
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = 5 \text{ V}, I_{C} = 30 \text{ mA}$	30			_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 50 \text{ mA}, I_B = 5 \text{ mA}$			1.5	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	$I_C = 50 \text{ mA}, I_B = 5 \text{ mA}$			1.5	V
Transition frequency	$f_T$	$V_{CB} = 30 \text{ V}, I_E = -20 \text{ mA}, f = 200 \text{ MHz}$		40		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 30 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			7	pF
(Common base, input open circuited)						

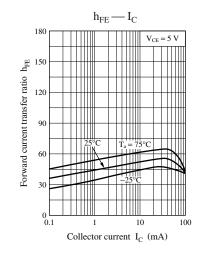
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

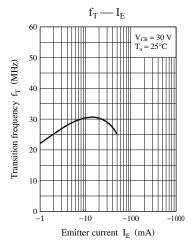


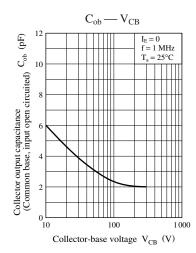












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